



SMT power inductors

Size 6.3 x 6.3 x 2.5 (mm)

Series/Type: B82462G2

The following products presented in this data sheet are being withdrawn.

Ordering Code	Substitute Product	Date of Withdrawal	Deadline Last Orders	Last Shipments
B82462G2*		2012-03-16	2012-09-28	2013-03-29

For further information please contact your nearest EPCOS sales office, which will also support you in selecting a suitable substitute. The addresses of our worldwide sales network are presented at www.epcos.com/sales.

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SMD
Rated inductance 0.82 ... 330 μ H
Rated current 0.22 ... 3.25 A

Construction

- Ferrite core
- Magnetically shielded
- Winding: enamel copper wire
- Winding welded to terminals

Features

- Temperature range up to +150 °C
- High rated current
- Low DC resistance
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020D
- Qualified to AEC-Q200
- RoHS-compatible

Applications

- Filtering of supply voltages
- Coupling, decoupling
- DC/DC converters
- Automotive electronics
- Industrial electronics

Terminals

- Base material CuSn6
- Layer composition Ag, Sn (lead-free)¹⁾
- Electro-plated

Marking

- Marking on component:
Manufacturer, L value (nH, coded),
L tolerance (coded), manufacturing date (YWWD)
- Minimum data on reel:
Manufacturer, ordering code, L value,
quantity, date of packing

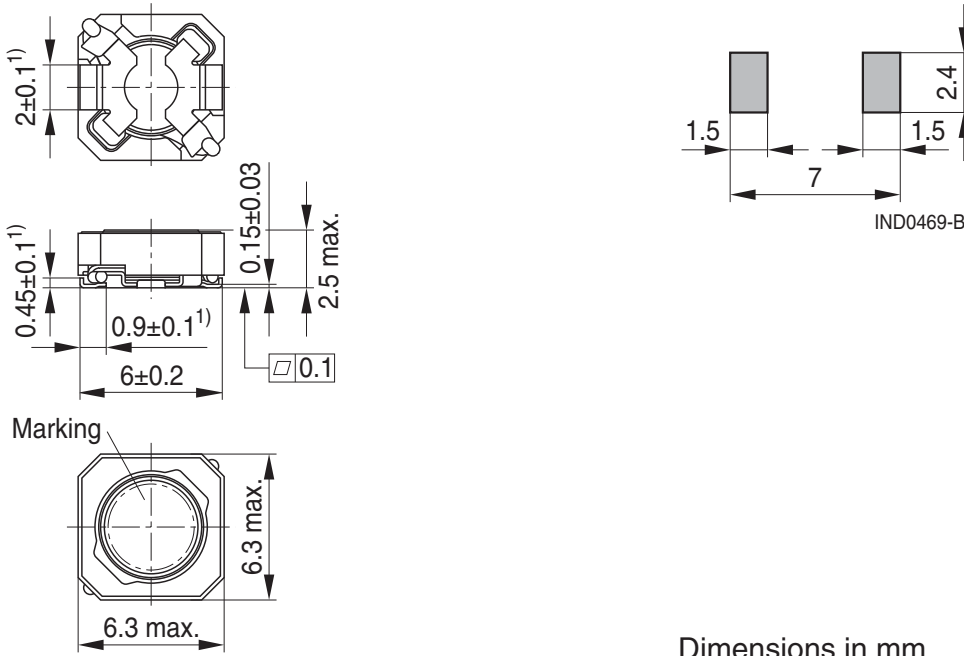
Delivery mode and packing unit

- 12-mm blister tape, wound on 330-mm \varnothing reel
- Packing unit: 2500 pcs./reel

¹⁾ Ni-barrier-plated terminals on request (B82462G2*50).

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Dimensional drawing and layout recommendation



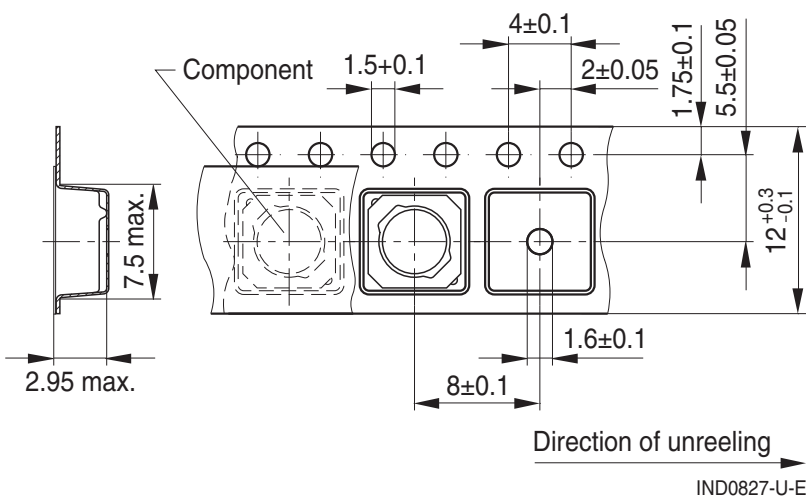
Dimensions in mm

1) Soldering area

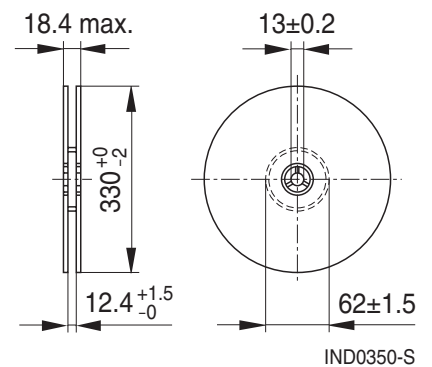
IND0470-D-E

Taping and packing

Blister tape



Reel



Dimensions in mm

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Technical data and measuring conditions

Rated inductance L_R	Measured with impedance analyzer Agilent 4294A at frequency f_L , 0.1 V, +20 °C
Rated temperature T_R	+85 °C
Rated current I_R	Max. permissible DC with temperature increase of ≤ 40 K at rated temperature
Saturation current I_{sat}	Max. permissible DC with inductance decrease $\Delta L/L_0$ of approx. 10%
DC resistance R_{max}	Measured at +20 °C
Solderability (lead-free)	Dip and look method Sn95.5Ag3.8Cu0.7: +(245 ±5) °C, (5 ±0.3) s Wetting of soldering area $\geq 90\%$ (based on IEC 60068-2-58)
Resistance to soldering heat	+260 °C, 40 s as referenced in JEDEC J-STD 020D
Climatic category	55/150/56 (to IEC 60068-1)
Storage conditions	Mounted: -55 °C ... +150 °C Packaged: -25 °C ... +40 °C, $\leq 75\%$ RH
Weight	Approx. 1.5 g

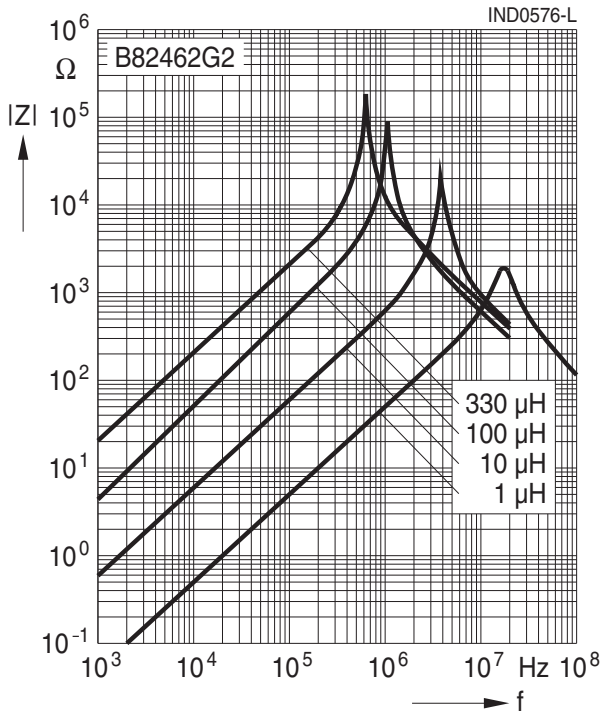
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Characteristics and ordering codes

L_R μH	Tolerance	f_L MHz	I_R A	I_{sat} A	R_{max} Ω	Ordering code
0.82	$\pm 20\% \triangleq M$	0.1	3.25	4.40	0.017	B82462G2821M000
1.0		0.1	3.25	4.25	0.017	B82462G2102M000
1.2		0.1	3.10	3.60	0.019	B82462G2122M000
1.8		0.1	2.75	3.00	0.022	B82462G2182M000
2.2		0.1	2.30	2.55	0.032	B82462G2222M000
3.3		0.1	2.00	2.05	0.040	B82462G2332M000
4.7		0.1	1.60	1.80	0.061	B82462G2472M000
6.8		0.1	1.45	1.48	0.078	B82462G2682M000
10		0.1	1.25	1.28	0.106	B82462G2103M000
15		0.1	1.02	1.02	0.160	B82462G2153M000
22		0.1	0.83	0.83	0.245	B82462G2223M000
33		0.1	0.68	0.68	0.345	B82462G2333M000
47		0.1	0.62	0.56	0.420	B82462G2473M000
68		0.1	0.48	0.47	0.635	B82462G2683M000
100		0.1	0.41	0.41	0.950	B82462G2104M000
150		0.1	0.33	0.31	1.480	B82462G2154M000
220		0.1	0.28	0.26	2.10	B82462G2224M000
330		0.1	0.22	0.20	3.25	B82462G2334M000

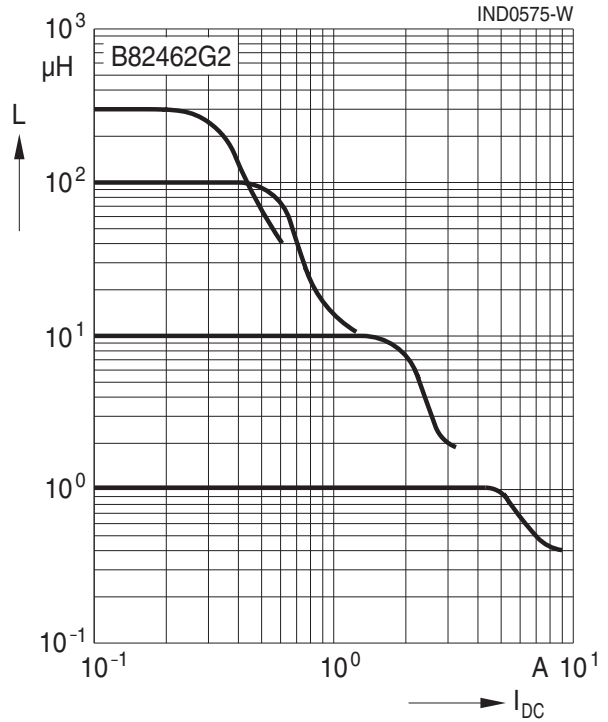
1) For Ni-barrier-plated terminals replace the last two digits "00" by "50".

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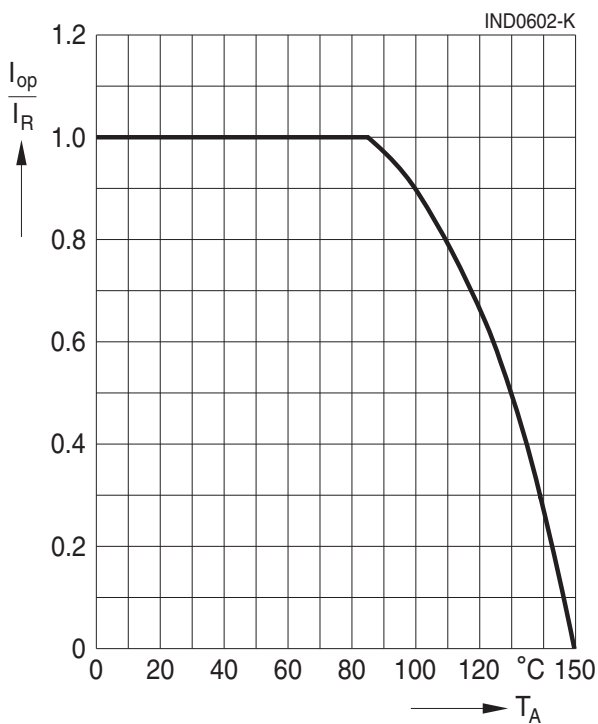
Impedance $|Z|$ versus frequency f
 measured with impedance analyzer
 Agilent 4294A, typical values at +20 °C



Inductance L versus DC load current I_{DC}
 measured with LCR meter Agilent 4275A,
 typical values at +20 °C



Current derating I_{op}/I_R
versus ambient temperature T_A
 (rated temperature $T_R = +85$ °C)



Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule we are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether a product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet (www.tdk-electronics.tdk.com/material). Should you have any more detailed questions, please contact our sales offices.
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We also **reserve the right to discontinue production and delivery of products**. Consequently, we cannot guarantee that all products named in this publication will always be available. The aforementioned does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.
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